

Fabrication Parameters:

Number of layers:	2
Board name:	first.brd
Board width (dimension X):	4.249213 in
Board length (dimension Y):	3.637008 in
Board thickness:	0.061811 in
Copper thickness outer layers:	0.001378 in
Copper thickness inner layers:	undefined
Solder sides:	Both Sides
Silkscreen sides:	Top Side
Number of SMD pads on top:	0
Number of SMD pads on bottom:	0
Number of blind or buried hole types:	0
Minimum trace width (track width):	0.012000 in
Minimum SMD pitch:	0.006000 in
Minimum hole size:	0.032000 in

Assembly Parameters:

Number of different packages:	10
Number of BGAs:	0
Number of QFNs:	0
Number of fine pitch packages:	0
Number of other SMDs:	0
Number of thru hole packages:	17
SMDs on both sides:	No